SemTron Microtech Corporation

SMC4923

-30V Dual P-Channel Enhancement Mode MOSFET

DESCRIPTION

The SMC4923 is the Dual P-Channel logic enhancement mode power field effect transistor is produced using high cell density. advanced trench technology to provide excellent $R_{DS(ON)}$.
This device is suitable for use as a load switch or in PWM and gate charge for most of the synchronous buck converter applications.

SMC4923M-TRG ROHS Compliant This is Halogen Free

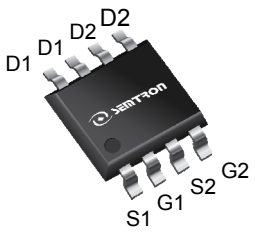
FEATURE

- ***-30V/-9.0A, $R_{DS(ON)}$ =10mΩ(typ)@V_{GS} =-20V***
- ***-30V/-8.0A, $R_{DS(ON)}$ =12mΩ(typ)@V_{GS} =-10V***
- ***-30V/-5.0A, $R_{DS(ON)}$ =16mΩ(typ)@V_{GS} =-4.5V***
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOP-8 package design

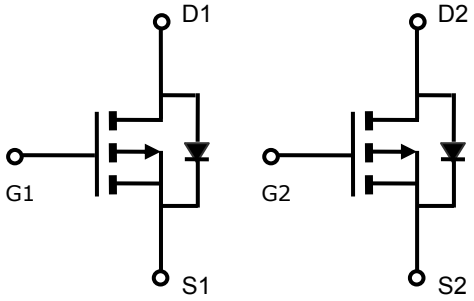
APPLICATIONS

- High Frequency Point-of-Load Synchronous
- Newworking DC-DC Power System
- Load Switch

PIN CONFIGURATION



SOP-8
Top View



PART NUMBER INFORMATION

STP 4923 M - TR G a b c d e	**a : Company name.** **b : Product Serial number.** **c : Package code** **d : Handling code** **e : Green produce code**

■ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
SMC4923M-TRG	M : SOP-8	TR : Tape&Reel	2.5K/Reel

※ Year Code : 0 ~ 9, 2010 : 0
※ Week Code : A(1~2) ~ Z(53~54)
※SOP-8 : Only available in tape and reel packaging.

■ABSOLUTE MAXIMUM RATINGS (T_A = 25℃ Unless otherwise noted)

Symbol	Parameter		Typical	Unit
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		±25	V
I_D	Continuous Drain Current (T_C=25°C) [A]	V_{GS}=10V	-9	A
	Continuous Drain Current (T_C=70°C)		-7	A
I_{DM}	Pulsed Drain Current[B]		-40	A
E_{AS}	Single Pulse Avalanche energy L=0.1mH [C]		50	mJ
P_D	Power Dissipation	T_A=25°C T_A=70°C	2.0 1.4	W
T_J	Operation Junction Temperature		-55 to150	°C
T_{STG}	Storage Temperature Range		-55 to150	°C

Note:
A.The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.
B.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

Absolute maximum ratings are those values beyond which the device could be permanently damaged.
Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■THERMAL DATA

Symbol	Parameter		Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient[A]	Steady-State	-	65	°C/W
$R_{\theta JL}$	Thermal Resistance Junction to Lead[A]	Steady-State	-	45	°C/W

■ELECTRICAL CHARACTERISTICS(T_J = 25℃ Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS} =0V,I_D =-250μA	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} =V_{GS},I_D =-250μA	-1.0		-2.5	V
I_{GSS}	Gate Leakage Current	V_{DS} =0V,V_{GS}=±25V			±100	nA
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} =-24V,V_{GS} =0V			-1	μA
		V_{DS} =-24V,V_{GS} =0V T_J =55°C			-5	
$R_{DS(ON)}$	Drain-source On-Resistance[B]	V_{GS} =-20V,I_D=-12.0A V_{GS} =-10V,I_D=-10.0A V_{GS} =-4.5V, I_D=-6.0A		10 12 16	13 14 20	mΩ
G_{fs}	Forward Transconductance	V_{DS} =-5V,I_D =-10.0A		10.5		S
Source-Drain Doide						
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.75		V
I_S	Continuous Source Current[AD]				-10	A
Dynamic Parameters						
Q_g	Total Gate Charge	V_{DS} =-15V, V_{GS} =-4.5V, I_D =-8.0A		15		nC
Q_{gs}	Gate-Source Charge			4.1		
Q_{gd}	Gate-Drain Charge			6.4		
C_{iss}	Input Capacitance	V_{DS} =-15V, V_{GS} =0V, f =1MHz		2350		pF
C_{oss}	Output Capacitance			220		
C_{rss}	Reverse Transfer Capacitance			152		
$t_{d(on)}$	Turn-On Time	V_{DD}=15V, V_{GS}=-10V, I_D=-5A, R_G=6Ω		9.4		nS
T_r				22		
$t_{d(off)}$	Turn-Off Time			62		
t_f				14.6		

Note:

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_C=25°C.

B. The data tested by pulsed , pulse width ≦ 300uS , duty cycle ≦ 2%

C. The EAS data shows Max. rating . The test condition is V_{DD}=-25V,V_{GS}=-10V,L=0.1mH.

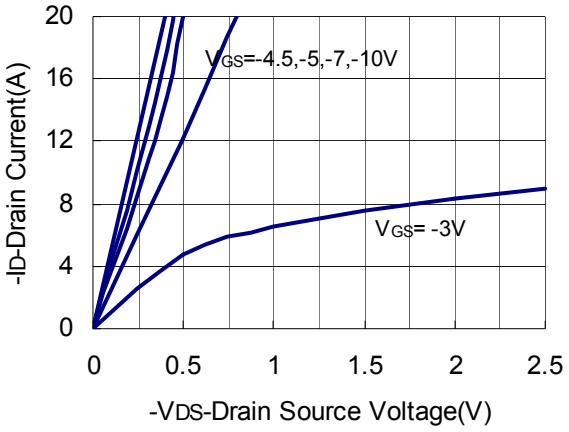
D. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

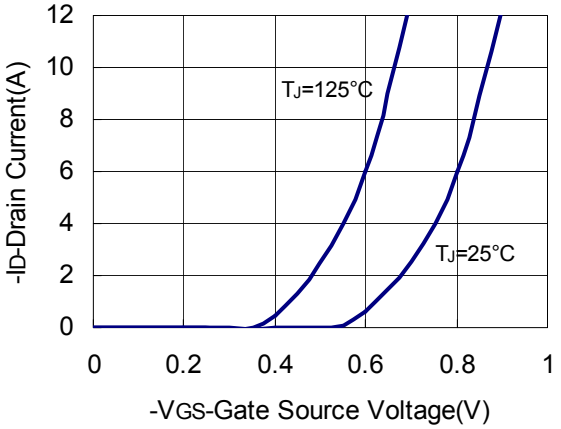
We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.

TYPICAL CHARACTERISTICS (25℃ Unless Note)

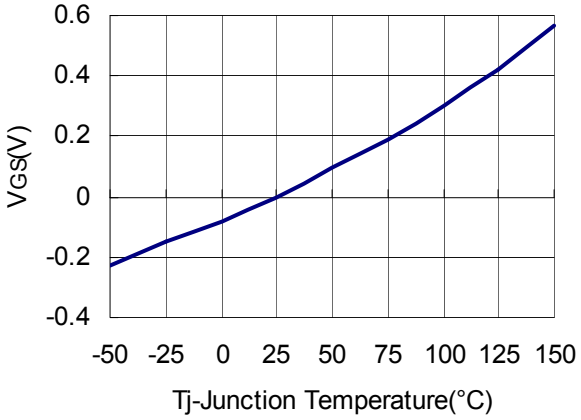
Output Characteristics



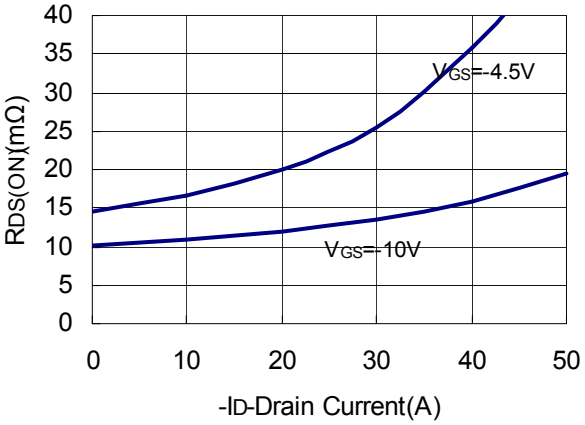
Transfer Characteristics



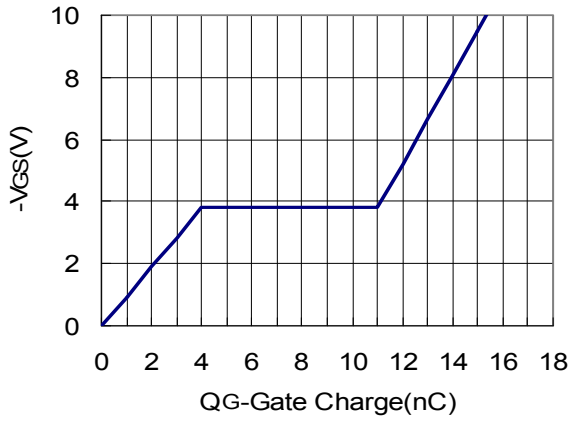
Gate Threshold Voltage



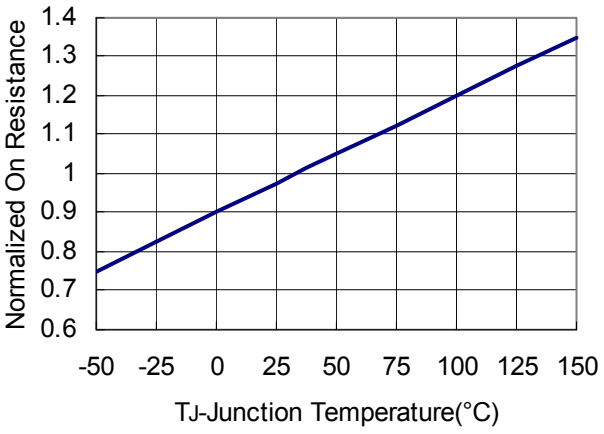
Drain Source On Resistance



Gate Charge

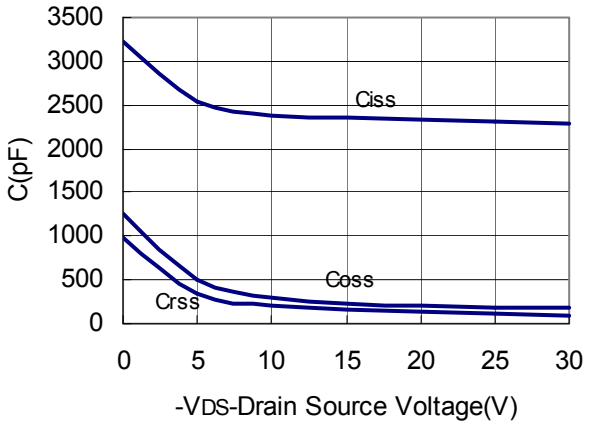


Drain Source On Resistance

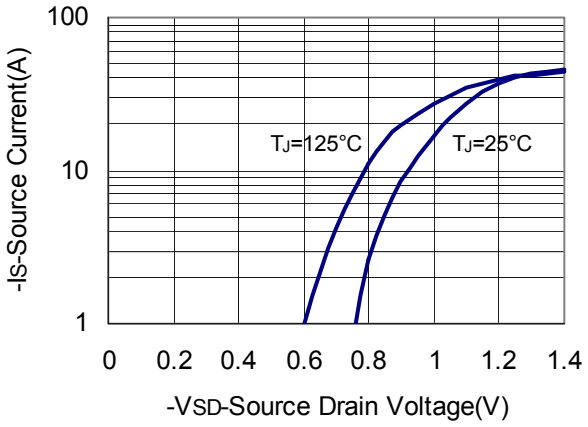


TYPICAL CHARACTERISTICS (25℃ Unless Note)

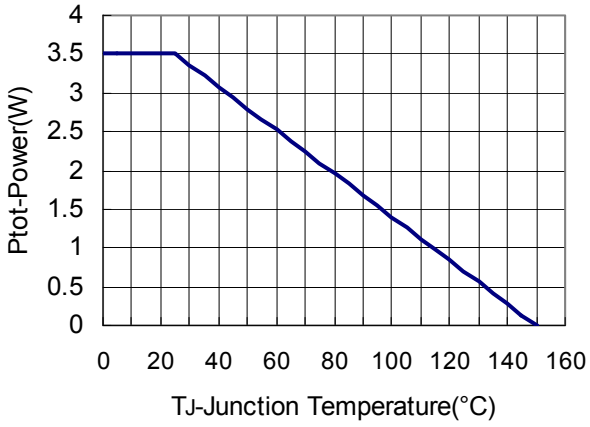
Capacitance



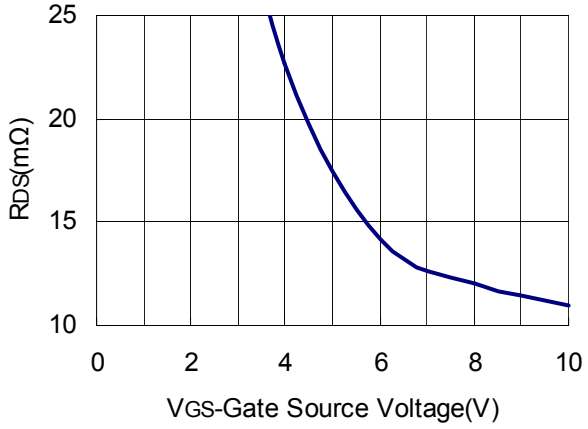
Source Drain Diode Forward



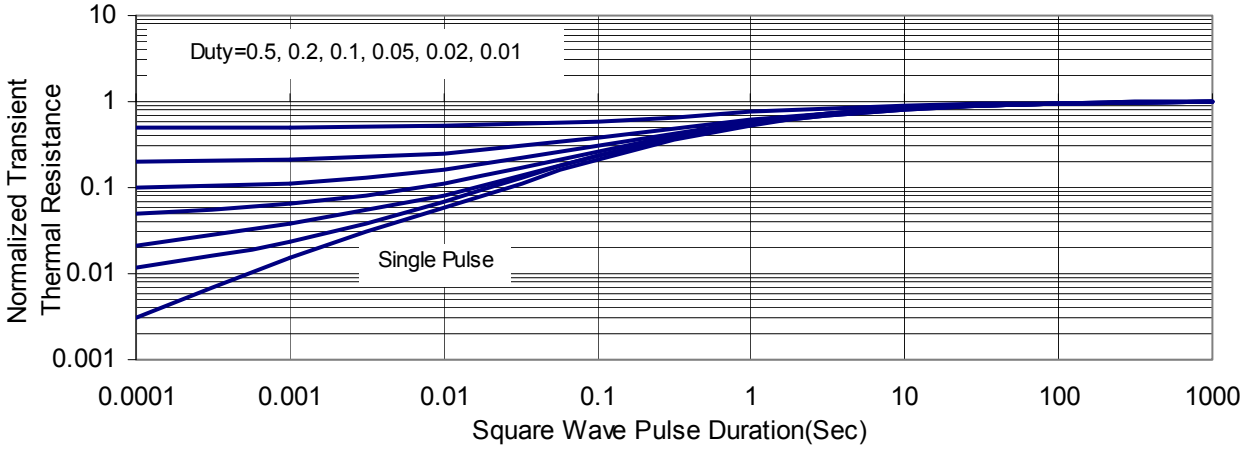
Power Dissipation



On Resistance VS Gate Source Voltage



Thermal Transient Impedance



SOP-8 PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.040	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°